

MEDIUM POWER LINEAR AMPLIFIER

Typical Applications

- PCS Communication Systems
- 2.5GHz ISM Band Applications
- Wireless LANs

- Commercial and Consumer Systems
- Portable Battery Powered Equipment

Product Description

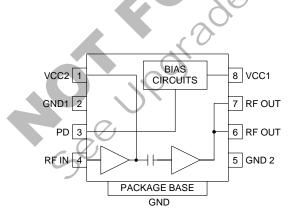
The RF2128 is a medium-power, high-efficiency, linear amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in 2.45 GHz ISM applications such as WLAN and POS terminals. The part also will function as the final stage in digital PCS phone transmitters requiring linear amplification operating between 1900MHz and 2200MHz, with over 100 mW transmitted power, or as the driver stage for the RF2125 high power amplifier. A simple power down function is included for TDD operation.

.057 MAX
.050
.050
.050
.017
.013
.006
.004
.000
.017
.013
.006
.004

Package Style: SOP-8-C

Optimum Technology Matching® Applied

- ☐ Si BJT
- **▼** GaAs HBT
- ☐ GaAs MESFET
- ☐ Si Bi-CMOS ☐ SiGe HBT ☐ Si CMOS



Functional Block Diagram

Features

- Single 3.0V to 6.5V Supply
- 100mW Linear Output Power
- 25dB Small Signal Gain
- 30% Efficiency
- Digitally Controlled Power Down Mode
- 1900MHz to 2500MHz Operation

Ordering Information

RF2128 Medium Power Linear Amplifier RF2128 PCBA Fully Assembled Evaluation Board

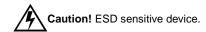
RF Micro Devices, Inc. 7625 Thorndike Road Greensboro, NC 27409, USA Tel (336) 664 1233 Fax (336) 664 0454 http://www.rfmd.com

Rev A3 010112

RF2128

Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage (V _{CC})	+7.5	V_{DC}
Power Down Voltage (V _{PD})	+5.5	V
DC Supply Current	125	mA
Input RF Power	+12	dBm
Output Load VSWR	20:1	
Operating Case Temperature	-40 to +100	°C
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



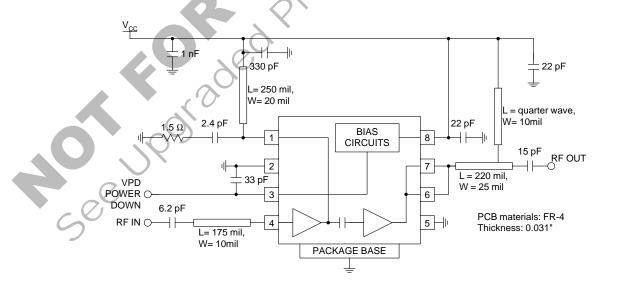
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Parameter	Specification		Unit	Condition		
Farameter	Min.	Тур.	Max.	Onit	Condition	
Overall					T=25 °C, V _{CC} =5V, V _{PD} =5.0V, Freq=2400MHz	
Frequency Range		1900 to 2500		MHz		
Maximum Output Power		>+20		dBm	V_{CC} =5.0V, V_{PD} =5.0V, P_{IN} =-3.0dBm	
Maximum Output Power		>+23		dBm	V _{CC} =6.0V, V _{PD} =5.5V, P _{IN} =0dBm	
Total CW Efficiency		30		%	Maximum output	
Small-signal Gain		25		dB	N V	
Second Harmonic		-25		dBc		
Third Harmonic		-22		dBc		
Isolation		15		dB	V _{PD} =0.2V	
Input VSWR		2:1				
Input Impedance		50		Ω		
Noise Figure		7		dB		
Two-tone Specification			. (
Average Two-Tone Power		+17		dBm	PEP-3dB	
IM ₃		-24		dBc	P _{OUT} =+14dBm for each tone	
IM ₅		-36		dBc	P _{OUT} =+14dBm for each tone	
IM7		-44	\bigcirc	dBc	P _{OUT} =+14dBm for each tone	
Two-Tone Power-Added Efficiency		36		%		
Power Down Control		7				
Power Down "ON"		V _{CC}		V	Voltage supplied to the input; device is "on"	
Power Down "OFF"	0		1.2	V	Voltage supplied to the input; device is "off"	
Power Supply						
Voltage	5.0	5		V	Specifications	
		3.0 to 6.5		V	Operating	
Current	\bigcirc	50	65	mA	Operating Idle	
		85		mA	At maximum output power	
Current			10	μΑ	Power Down	

2-86 Rev A3 010112

Pin	Function	Description	Interface Schematic
1	VCC2	Power supply for the driver stage and interstage matching. External matching on this pin is required to optimize the gain. The matching on this port also greatly affects the input impedance. A decoupling capacitor of 330pF is required, together with a series RC for tuning for maximum gain at the desired frequency. See the application information for details.	
2	GND1	Ground connection for the driver stage. Keep traces physically short and connect immediately to the ground plane for best performance.	
3	PD	Power Down control. When this pin is "low", all circuits are shut off. A "low" is typical 1.2 V or less at room temperature. When this pin is "high", all circuits are operating normally. A "high" is V_{CC} . If PD is below V_{CC} , output power and performance will be degraded. This could be used to obtain some gain control, but results are not guaranteed.	6
4	RF IN	RF Input. This is a 50Ω input, but the actual impedance depends on the matching provided on pin 1. An external DC blocking capacitor is required if this port is connected to a DC path to ground.	
5	GND2	Ground connection for the output stage. Keep traces physically short and connect immediately to the ground plane for best performance.	
6	RF OUT	RF Output and power supply for the output stage. Bias for the output stage needs to be provided on this pin. This can be done through a quarter-wave microstrip that is RF grounded on the other end. For matching to 50Ω , an external series microstrip line is required.	8
7	RF OUT	Same as pin 6.	
8	VCC1	Power supply for the bias circuits. An external RF bypass capacitor of 22pF is required. Keep the traces to the capacitor as short as possible, and connect the capacitor immediately to the ground plane.	
Pkg Base	GND	Ground connection. The backside of the package should be connected to the ground plane through a short path, i.e., vias under the device may be required.	

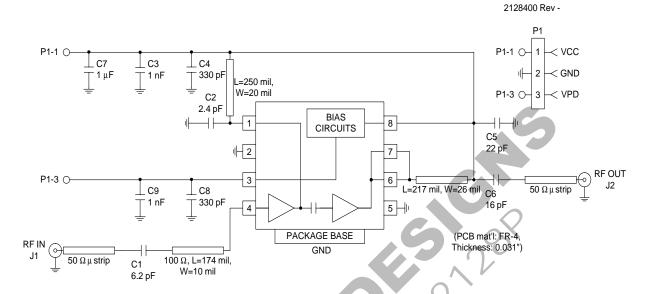
Application Schematic 2450MHz



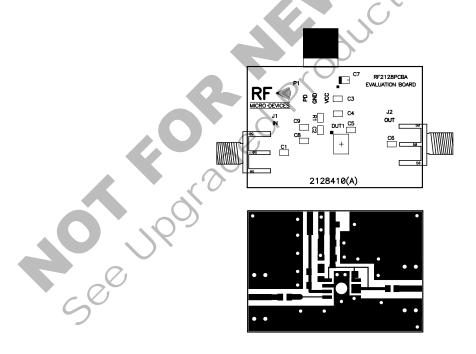
Rev A3 010112 2-87

Evaluation Board Schematic 2450MHz Operation

(Download Bill of Materials from www.rfmd.com.)



Evaluation Board Layout 1.547" x 1.068"



2-88 Rev A3 010112